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ROHM Co., Ltd.
April 1, 2024

RB-D62Q2524GD40

User's Manual

Issue Date: March 8, 2022

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LAPIS Technology Co., Ltd.

2-4-8 Shinyokohama, Kouhoku-ku, Yokohama 222-8575, Japan
<https://www.lapis-tech.com/en/>

Preface

This manual describes about the ML62Q2524 Reference Board : RB-D62Q2524GD40.

Refer to following documents when necessary.

- ML62Q2500 Group User's Manual
Provides the detailed information about the microcontroller ML62Q2500 Group.

- EASE1000 V2 User's Manual
Provides the information on how to use the On-chip emulator EASE1000 V2.

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1. Overview

1.1. Features

The RB-D62Q2524GD40 can be used for learning 'how to use' the ML62Q2524, on which the user needs to provide additional external components if necessary. By using the RB-D62Q2524GD40 together with the LAPIS Technology's on-chip emulator EASE1000 V2 and the provided software development environment, the user can develop software, debug and program the Flash. Also, by connecting an external power supply to RB-D62Q2524GD40, it can be used independently without connecting a EASE1000 V2.

Before using RB-D62Q2524GD40, be sure to understand and keep in mind the following information.

1.1.1. Features

- The board is provided with ML62Q2524 40pin WQFN.
- Mounted with the linked connector to EASE1000 V2.
- Through-holes for connecting the pins of LSI to external peripheral boards.
- Power supply is selectable; supplied from the on-chip emulator EASE1000 V2 or CN1_3pin.
- Mounted with Crystal (32.768KHz)
- Mounted with LED (P20,P21,P22).
- Foot pattern with components for Successive Approximation Type A/D Converter is available (P30,P31,P32,P33).

1.1.2. Hardware specifications

Table 1 shows the hardware specifications of RB-D62Q2524GD40.

Table 1 Hardware specifications

Mounted LSI	U1 : ML62Q2524 40pin WQFN
Other Mounted components	PWR: Jumper for selecting the power supply input (3pin pin-header and short pin)
	J1: Jumper for selecting TEST1_N pin (3pin pin-header and short pin)
	J2: Jumper for selecting P00/TEST0 pin (3pin pin-header and short pin)
	P20-P22: LEDs
	R1-R3: Resistors for LEDs by P20 to P22
	J3-J5: Jumper Chip for connecting LEDs
	X1, C3, C4: Crystal Oscillator (32.768kHz) and capacitors
	CNE: Connector for EASE1000 V2(14pin connector)
	C1, C3: Capacitors for VDD and VDDL
	R4: Pull-up resistor for RESET_N
Pads (or/and) Through holes for mounting components	CN1-CN2: Connectors for user application system (24pin, 2.54mm pitch, ϕ 0.9mm)
	C2: Capacitors for VDD
	C6-C10, J8: Capacitors and jumper chip for Successive Approximation Type A/D Converter
	J6-J7: CN1 connection jumper chip
Power check pin	VDD, VSS, UVDD: ϕ 0.8mm
Operating voltage	+1.8V to +5.5V
Board size	55.88 mm x 93.98 mm

For more information about the connection of the mounted components, see the schematic.

1.2. Outline Diagram

Fig. 1 shows the RB-D62Q2524GD40.

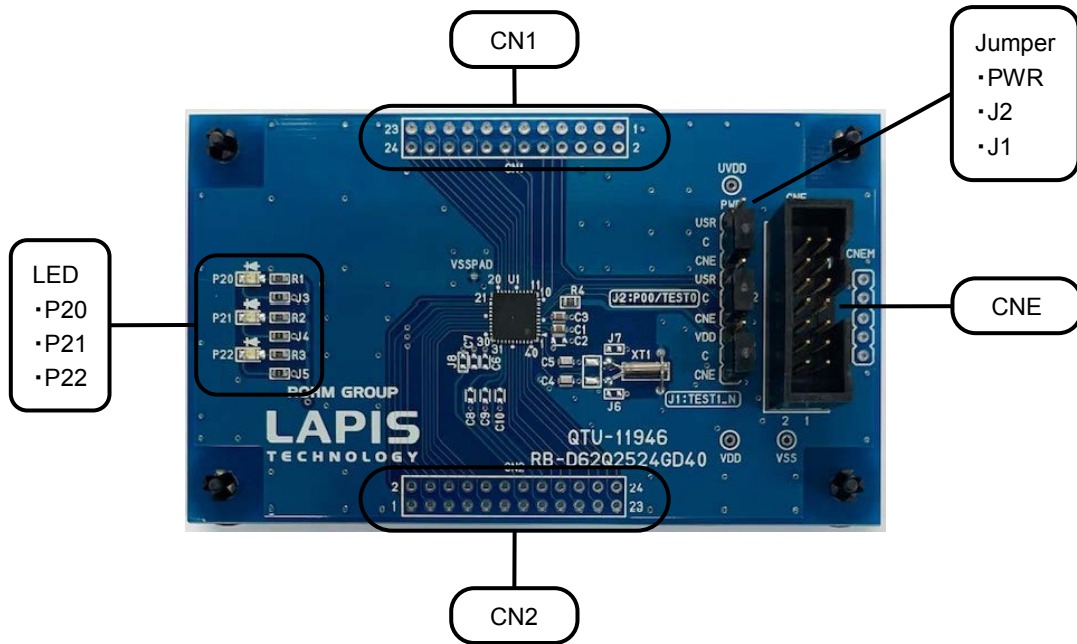


Fig. 1 Outline Diagram

2. Function

2.1. Power Circuit

The input to V_{DD} can be selected from 3.3VOUT of EASE1000 V2 or CN1_3pin by PWR jumper.

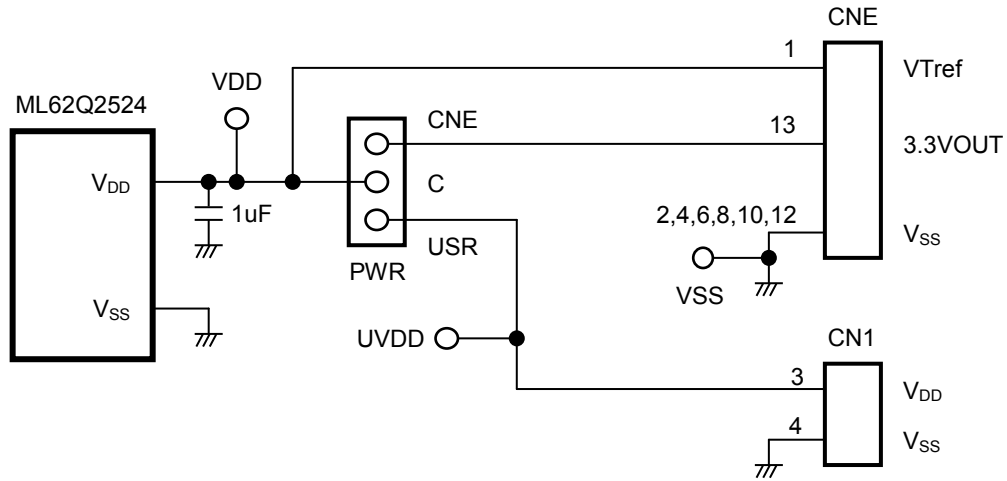


Fig. 2 Power Circuit

[Note]

The power supply ON/OFF procedure in case of setting PWR jumper to the USB-side when using EASE1000 V2.

- The procedure of power supply ON
 1. The USB cable of EASE1000 V2 is connected.
 2. The power supply of user's target system is turned on.

- The procedure of power supply OFF
 1. The power supply of user's target system is turned off
 2. The USB cable of EASE1000 V2 is removed

2.2. Connection for EASE1000 V2 (CNE)

EASE1000 V2 can be used if J1 and J2 jumper are set to “CNE”.

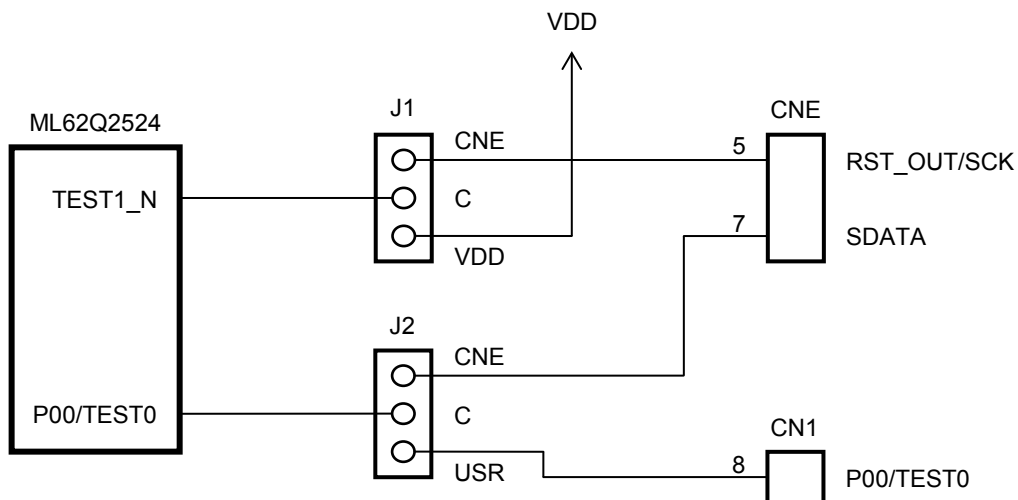


Fig. 3 EASE1000 V2 Interface

[Note]

P00/TEST0 pin:

P00/TEST0 pin of ML62Q2524 is initially set as a pull-up input mode

When using EASE1000 V2, do not set it as an output mode by using an application program, otherwise EASE1000 V2 cannot communicate with the ML62Q2524.

2.3. LED (P20, P21, P22)

The P20-P22 pins are ports that can directly drive LED. The Ports are connected to the LEDs through jumper-chip. Remove the jumper-chip when not using the LEDs.

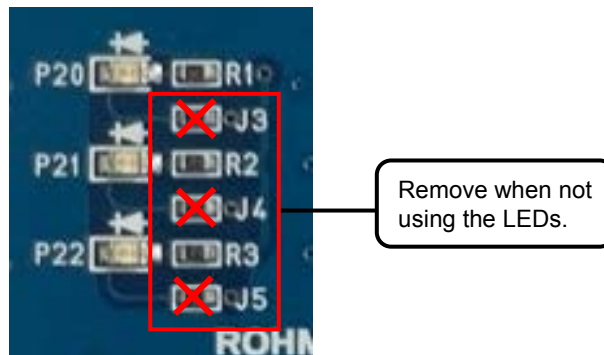


Fig. 4 Jumper-chip removal of LEDs

2.4. XT0/PIO0, XT1/PIO1

RB-D62Q2524GD40 can be mounted with cylinder type or SMD type crystal oscillator.

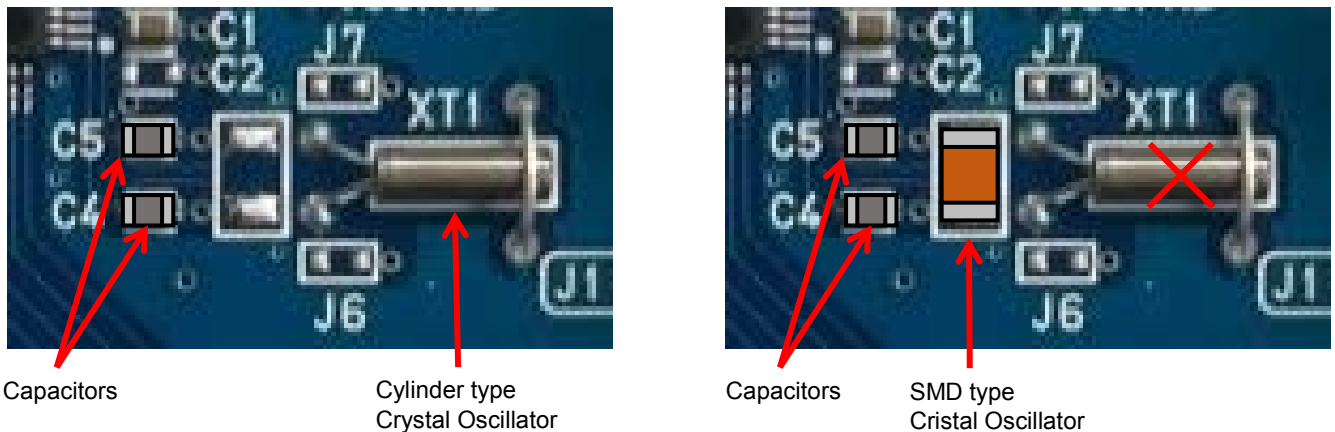


Fig. 5 Example of processing of Crystal Oscillator

2.5. P30, P31, P32, P33

When the P30 pin is used as VREF function of the successive approximation type A/D converter, C6, C7 can implement a bypass capacitor. In addition, VDD can be connected by mounting the J8 jumper chip.

When P31, P32, P33 pin is used as AIN8, AIN9, AIN10 function of the successive approximation type A/D converter, the C8 and C9, C10 can implement a by-pass capacitor.

Fig. 6 shows the connection diagram.

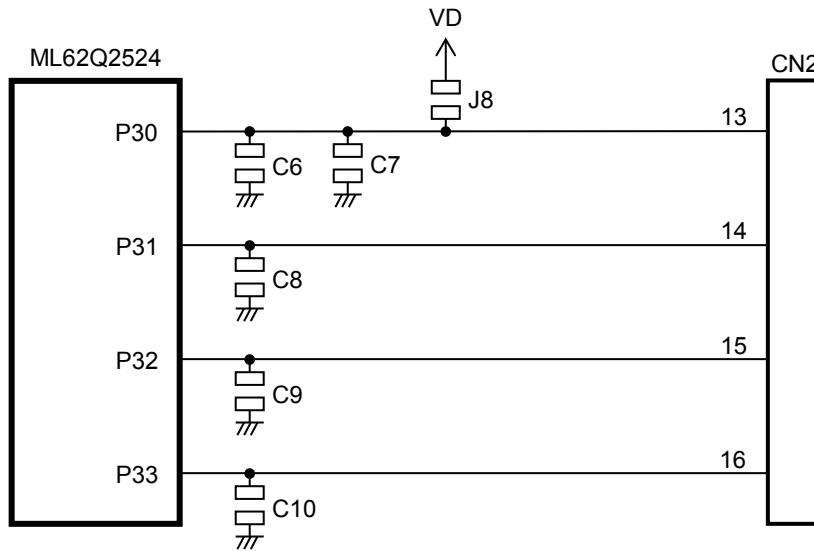


Fig. 6 P30, P31, P32, P33 Circuit

3. User Interface

3.1. CN1, CN2

Table 2 shows the pin list of the RB-D62Q2524GD40 user interface connection CN1 and CN2.

Table 2 CN1, CN2

CN1 Pin No.	Connection destination			CN2 Pin No.	Connection destination		
	Device	Pin No.	Name		Device	Pin No.	Name
1	J6	1	XT0	1	ML62Q2524	25	P17
2	J7	1	XT1	2	ML62Q2524	26	P20
3	PWR	USR	VDD	3	ML62Q2524	27	P21
4	-	-	VSS	4	ML62Q2524	28	P22
5	-	-	N.C.	5	ML62Q2524	29	P23
6	ML62Q2524	6	RESET_N	6	ML62Q2524	30	P24
7	-	-	N.C.	7	ML62Q2524	31	P25
8	J2	USR	P00/TEST0	8	ML62Q2524	32	P26
9	ML62Q2524	9	P02	9	ML62Q2524	33	P27
10	ML62Q2524	10	P03	10	-	-	N.C.
11	-	-	N.C.	11	-	-	N.C.
12	-	-	N.C.	12	-	-	N.C.
13	ML62Q2524	13	P54	13	ML62Q2524	37	P30
14	ML62Q2524	14	P55	14	ML62Q2524	38	P31
15	-	-	N.C.	15	ML62Q2524	39	P32
16	-	-	N.C.	16	ML62Q2524	40	P33
17	ML62Q2524	17	P04	17	ML62Q2524	41	P34
18	ML62Q2524	18	P05	18	ML62Q2524	42	P35
19	ML62Q2524	19	P06	19	ML62Q2524	43	P36
20	ML62Q2524	20	P07	20	-	-	N.C.
21	ML62Q2524	21	P10	21	ML62Q2524	45	P70
22	ML62Q2524	22	P11	22	ML62Q2524	46	P71
23	ML62Q2524	23	P12	23	ML62Q2524	47	P72
24	ML62Q2524	24	P13	24	ML62Q2524	48	P73

N.C. : Not Connected

3.2. CNE

Table 3 shows the pin list of the RB-D62Q2524GD40 user interface connection CNE.

Table 3 CNE

CNE		Connection		
Pin No.	Name	Parts	Pin No.	ML62Q2524 Pin Name
1	VTref	-	-	VDD
2	GND	-	-	VSS
3	VPP	-	-	N.C.
4	GND	-	-	VSS
5	RST_OUT/SCK	J1	CNE	TEST1_N
6	GND	-	-	VSS
7	SDATA	J2	CNE-	P00/TEST0
8	GND	-	-	VSS
9	VDDL	-	-	N.C.
10	GND	-	-	VSS
11	N.C.	-	-	N.C.
12	GND	-	-	VSS
13	3.3VOUT	PWR	CNE	VDD
14	N.C.	-	-	N.C.

N.C. : Not Connected

4. Precaution for usage

- (1) The RB-D62Q2524GD40 is an unfinished product and intended for research and development and for expert use in the research and development facility only. The RB-D62Q2524GD40 is not intended to be used for volume production or parts thereof.
- (2) Since the content specified herein is subject to change for improvement without notice, confirm the latest content when using the board.
- (3) See the other documents, the ML62Q2500 group user's manual and EASE1000 V2 user's manual when using the RB-D62Q2524GD40.
- (4) Confirm the final electrical characteristics by using the mass production parts on your mass production boards.
- (5) LAPIS supports replacing the board for an initial failure soon after the shipment. However LAPIS doesn't support repairing the board.
- (6) RB-D62Q2524GD40 have signal patterns on the underside, it might work abnormally if using on conductive materials. Use it on insulating materials or having any preventable parts.

5. PCB specification, BOM list and Schematic

5.1. PCB specification

Fig. 7 shows the PCB dimensional outline diagram and layout of components.

PCB part number:
RB-D62Q2524GD40

Dimension:
55.88mm x 93.98mm

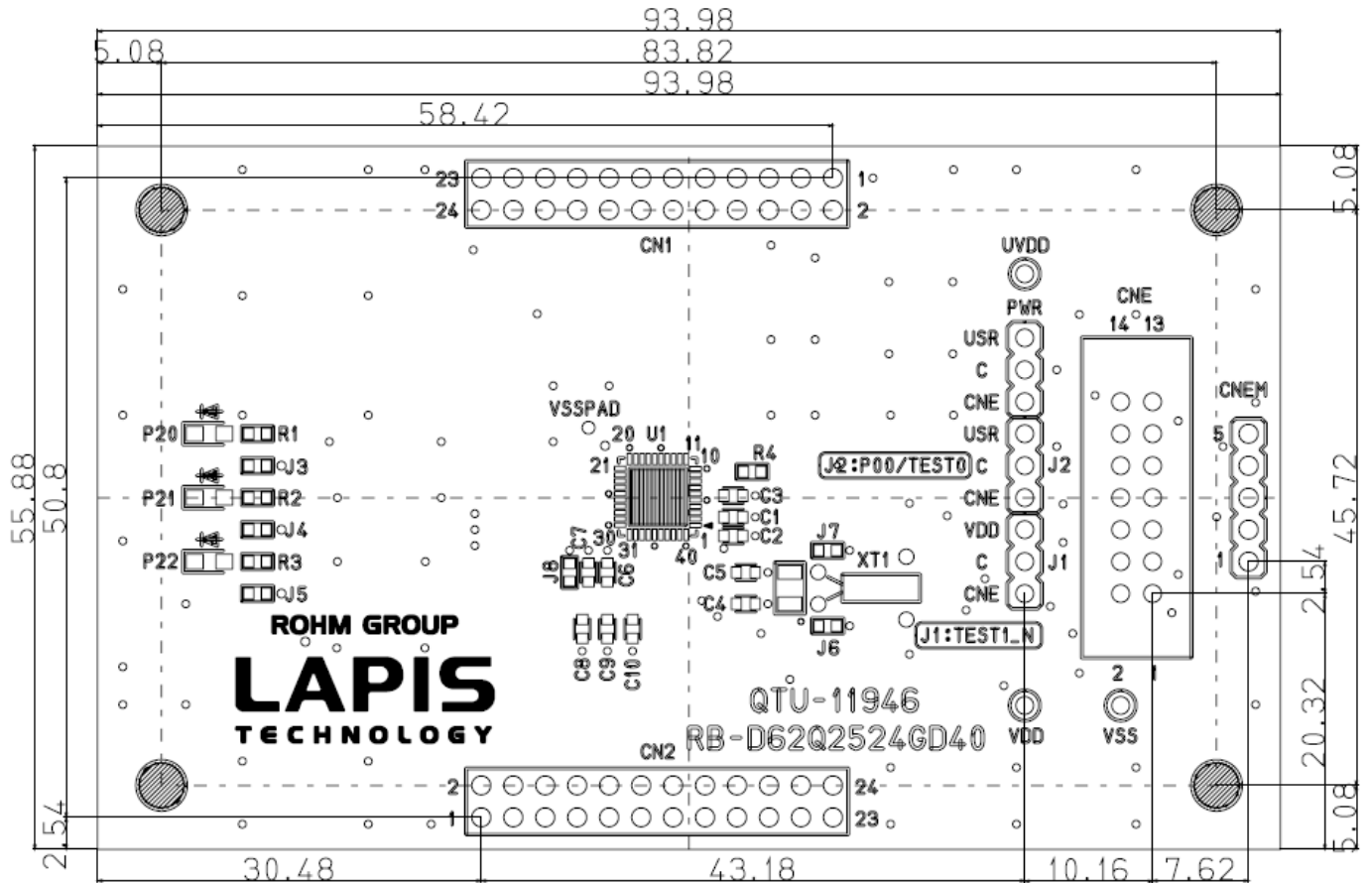


Fig. 7 PCB dimensional outline diagram and layout of components (Top view)

5.2. BOM list

Table 4 BOM list

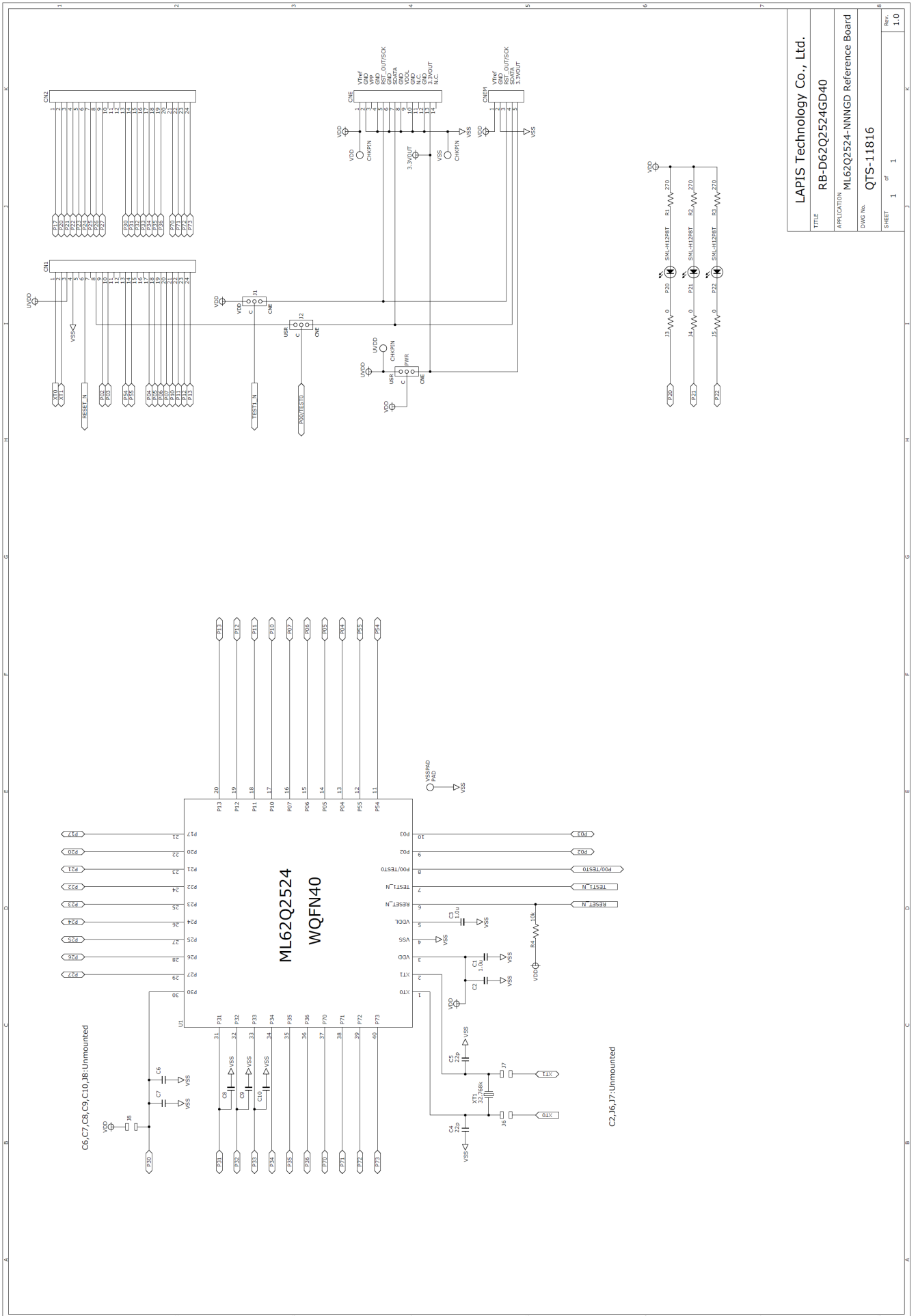
	Parts Number	Symbol	Contents	Qty.	Vendor
1	QTU-11946	RB-D62Q2524GD40	PCB	1	LAPIS Technology Co., Ltd.
2	C1608X7R1E105K080AB	C1, C3	Ceramic Capacitor 1.0 μ F/25V X7R	2	TDK Corporation
3	-	C2, C6, C7, C8, C9, C10	Unmounted	6	-
4	GRM1885C1H220JA01	C4, C5	Ceramic Capacitor 22pF/50V COG	2	Murata Manufacturing Co., Ltd.
5	A1-24PA-2.54DSA(71)	CN1, CN2	Unmounted	2	Hirose Electric Co., Ltd.
6	HIF3FC-14PA-2.54DSA(71)	CNE	14pin Header Connector	1	Hirose Electric Co., Ltd.
7	-	CNEM	Unmounted	1	-
8	A2-3PA-2.54DSA	J1, J2, PWR	3pin Header Connector	3	Hirose Electric Co., Ltd.
9	MCR03ERTJ000	J3, J4, J5	Resistor 0 Ω	3	Rohm Co., Ltd.
10	-	J6, J7, J8	Unmounted	3	-
11	SML-H12P8T	P20, P21, P22	LED Green	3	Rohm Co., Ltd.
12	MCR03EZPJ271	R1, R2, R3	Resistor 270 Ω \pm 5%	3	Rohm Co., Ltd.
13	MCR03EZPJ103	R4	Resistor 10k Ω \pm 5%	1	Rohm Co., Ltd.
14	ML62Q2524-NNNGD	U1	16-bit Microcontroller	1	LAPIS Technology Co., Ltd.
15	-	UVDD, VDD, VSS	Unmounted	3	-
16	-	VSSPAD	Unmounted	1	-
17	VT-200-F 12.5pF	XT1	X'tal 32.768kHz 12.5pF	1	Seiko Instruments Inc.
18	HIF3GA-2.54SP	-	Short pin	3	Hirose Electric Co., Ltd.

[Note]

- The diameter of through hole of CN1 and CN2 is 0.9 mm.
Using CN1 and CN2, the diameter of connector pin should use the connector below 0.9mm, such as 0.5mm.
- The parts may be changed into another parts with equivalent part special quality.

5.3. Schematic

The next page shows the schematic of RB-D62Q2524GD40.



LAPIS Technology Co., Ltd.	
TITLE	RB-D62Q2524GD40
APPLICATION	ML62Q2524-NNNGD Reference Board
DWG No.	QTS-11816
SHEET	1 of 1
Rev.	1.0

6. Revision History

Document No.	Issue Date	Page		Description
		Previous Edition	New Edition	
FEBL62Q2524RB-01	March 8, 2022	–	–	First edition.